Method For Manufacturing Compound Material Wafers and Method for Recycling a Used Donor Substrate

Abstract

The invention relates to a method for manufacturing compound material wafers comprising the steps and a method for recycling donor substrates obtained in a method for manufacturing compound material wafers, wherein in order to improve the recycling rate of the donor substrate, at least one thermal treatment step configured to at least partially reduce oxygen precipitates and/or nuclei is carried out.

Fig. 1